

LISTING OF CLAIMS

1. (Previously Amended) An electronic module, in particular a multichip module, comprising a multilayer wiring having at least one IC component applied on a component side thereof, said module being unilaterally covered on the component side with a hermetic case, and comprising a plurality of contact pads on a bottom side of the module through for contacting and integration of the module to a next higher assembly group level, the bottom side of the multilayer wiring constituting directly, without additional wiring substrate, the bottom side of the module, the component side of the multilayer wiring adhering to the hermetic case with its portions that are free from components, said hermetic case being formed by plastics overmolding, and in that the multilayer wiring has a height of less than approximately 100 μm .

2. (Original) A module according to claim 1, wherein the multilayer wiring is constituted by a sequence of structured metal planes which are electrically separated from each other by insulating layers and between which purposeful electric connections are established through vias.

3. (Previously Amended) A module according to claim 1, wherein solderable material is applied to the contact pads on the bottom side of the multilayer wiring, electrically connected to the component side through vias, for establishing contact with the next higher assembly group level.

4. (Original) A module according to claim 3, wherein the solderable material is applied in the form of solder balls

5. (Withdrawn) A method of making an electronic module according to claim 1, in which

- a multilayer wiring having contact pads on the bottom side thereof is applied only to the top side of a plate-shaped wiring substrate of rigid material,

- IC components and additional electronic components, respectively, are electrically and mechanically connected to the component level of the multilayer wiring,

- the component side of the multilayer wiring is provided with a hermetic case adhering in the portions thereof that are free from components,

- the rigid substrate material is removed again thereafter and the bottom side of the multilayer wiring which constitutes the bottom side of the module, is exposed, and said hermetic case is formed by unilateral plastics overmolding.

6. (Withdrawn) A method according to claim 4, wherein, prior to removal of the particular metallic substrate material in portions located underneath the contact pads, pits are etched into the wiring substrate from the bottom side, with solderable material being introduced into said pits thereafter.

7. (Withdrawn) A method according to claim 4, wherein the removal of the particular metallic substrate material takes place by dissolution of the same.

8. (Withdrawn) A method according to claim 7, wherein the dissolution takes place by wet chemical etching.

9. (Withdrawn) A method according to claim 4, wherein the removal of the substrate material takes place by stripping the wiring substrate from the multilayer wiring.